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**HANZAWA**(10) **Pub. No.: US 2023/0232135 A1**(43) **Pub. Date: Jul. 20, 2023**(54) **SOLID-STATE IMAGING DEVICE****Publication Classification**(71) Applicant: **SONY SEMICONDUCTOR  
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KANAGAWA (JP)(57) **ABSTRACT**(21) Appl. No.: **18/001,465**(22) PCT Filed: **Jun. 4, 2021**(86) PCT No.: **PCT/JP2021/021308**

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A solid-state imaging device includes a plurality of pixel regions. Each of the plurality of pixel regions includes a first photoelectric conversion unit and a second photoelectric conversion unit. The second photoelectric conversion unit overlaps the first photoelectric conversion unit when viewed in a light incident direction. At least one of the first photoelectric conversion unit and the second photoelectric conversion unit is an embedded unit. The first photoelectric conversion unit and the second photoelectric conversion unit are electrically connected to mutually different types of readout circuits.

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